

Product Change Notification - KSRA-20KRVB706

Date: 24 Oct 2017
Product Category: Memory; Sigma - Delta A/D Converters; 8-bit PIC Microcontrollers
Notification subject: CCB 2845 Final Notice: Qualification of ASSH as an additional assembly site for selected products of 160K wafer technology available in 8L SOIC package using CuPdAu bond wire
Notification text: **PCN Status:**
 Final notification.

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASSH as an additional assembly site for selected products of 160K wafer technology available in 8L SOIC package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at ANAP and NSEB Assembly site

Post Change:

Assembled at ANAP, NSEB and ASSH Assembly site

Pre and Post Change Summary:

	Pre Change		Post Change		
Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	UTAC Thai Limited (NSEB)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	UTAC Thai Limited (NSEB)	ASE-Shanghai (ASSH)
Wire material	Au Wire	Au Wire	Au Wire	Au Wire	CuPdAu Wire
Die attach material	8290	2200D	8290	2200D	EN4900G
Molding compound material	G600	G600	G600	G600	CEL-9240HF10AK
Lead frame material	C194	C194	C194	C194	C194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve productivity by qualifying ASSH as an additional assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
November 24, 2017 (date code: 1747)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2017					-->	October 2017					November 2017			
	09	10	11	12	13		40	41	42	43	44	45	46	47	48
Workweek															
Initial PCN Issue Date			X												
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date														X	

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

March 23, 2017: Issued initial notification.
October 24, 2017: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on November 24, 2017.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_KSRA-20KRVB706_Affected CPN.pdf](#)
 - [PCN_KSRA-20KRVB706_Qual Report.pdf](#)
 - [PCN_KSRA-20KRVB706_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Number (CPN)

PCN_KSRA-20KRVB706
CATALOG_PART_NBR
24AA128-I/SN
24AA128T-I/SN
24AA128T-I/SNRVF
24FC128-E/SN
24FC128-I/SN
24FC128T-E/SN
24FC128T-I/SN
24FC256-E/SN
24FC256-I/SN
24FC256T-E/SN
24FC256T-I/SN
25AA320A-I/SN
25AA320A-I/SNB22
25AA320AT-I/SN
25AA320AT-I/SNB22
25AA640A-E/SN
25AA640A-I/SN
25AA640AT-E/SN
25AA640AT-I/SN
25AA640AT-I/SNB23
25LC320A-E/SN
25LC320A-I/SN
25LC320AT-E/SN
25LC320AT-I/SN
25LC640A-E/SN
25LC640A-I/SN
25LC640AT-E/SN
25LC640AT-I/SN
HA7600-I/SN
HA7600T-I/SN
MCP3550-50E/SN
MCP3550-60E/SN
MCP3550T-50E/SN
MCP3550T-60E/SN
MCP3551-E/SN
MCP3551T-E/SN
MCP3553-E/SN
MCP3553T-E/SN
MCP6N11-001E/SN
MCP6N11-002E/SN
MCP6N11-005E/SN
MCP6N11-010E/SN
MCP6N11-100E/SN

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Affected Catalog Part Number (CPN)

PCN_KSRA-20KRVB706
CATALOG_PART_NBR
MCP6N11T-001E/SN
MCP6N11T-002E/SN
MCP6N11T-005E/SN
MCP6N11T-010E/SN
MCP6N11T-100E/SN
PIC12F609-E/SN
PIC12F609-I/SN
PIC12F609T-E/SN
PIC12F609T-I/SN
PIC12F609T-I/SN027
PIC12F615-E/SN
PIC12F615-I/SN
PIC12F615-I/SN083
PIC12F615T-E/SN
PIC12F615T-I/SN
PIC12F615T-I/SN020
PIC12F615T-I/SN043
PIC12F615T-I/SN051
PIC12F615T-I/SN057
PIC12F615T-I/SN058
PIC12F615T-I/SN071
PIC12F615T-I/SN076
PIC12F615T-I/SN079
PIC12F615T-I/SN083
PIC12F617-E/SN
PIC12F617-E/SN020
PIC12F617-E/SN031
PIC12F617-E/SN033
PIC12F617-E/SN034
PIC12F617-I/SN
PIC12F617-I/SN020
PIC12F617-I/SN021
PIC12F617-I/SN030
PIC12F617-I/SN032
PIC12F617-I/SN053
PIC12F617-I/SNAU
PIC12F617-I/SNC15
PIC12F617T-E/SN
PIC12F617T-E/SN020
PIC12F617T-E/SN024
PIC12F617T-E/SN026
PIC12F617T-E/SN027
PIC12F617T-E/SN031

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Affected Catalog Part Number (CPN)

PCN_KSRA-20KRVB706
CATALOG_PART_NBR
PIC12F617T-E/SN033
PIC12F617T-E/SN034
PIC12F617T-E/SN036
PIC12F617T-E/SN037
PIC12F617T-E/SN050
PIC12F617T-E/SN051
PIC12F617T-E/SN052
PIC12F617T-E/SN055
PIC12F617T-E/SN067
PIC12F617T-E/SN071
PIC12F617T-I/SN
PIC12F617T-I/SN020
PIC12F617T-I/SN021
PIC12F617T-I/SN022
PIC12F617T-I/SN023
PIC12F617T-I/SN025
PIC12F617T-I/SN028
PIC12F617T-I/SN030
PIC12F617T-I/SN032
PIC12F617T-I/SN038
PIC12F617T-I/SN043
PIC12F617T-I/SN044
PIC12F617T-I/SN045
PIC12F617T-I/SN048
PIC12F617T-I/SN053
PIC12F617T-I/SN059
PIC12F617T-I/SNAU
PIC12F617T-I/SNC15
PIC12F635-E/SN
PIC12F635-I/SN
PIC12F635-I/SN057
PIC12F635T-I/SN
PIC12F635T-I/SN041
PIC12F635T-I/SN043
PIC12F635T-I/SN047
PIC12F635T-I/SN050
PIC12F635T-I/SN058
PIC12F635T-I/SN066
PIC12F683-E/SN
PIC12F683-E/SN084
PIC12F683-I/SN
PIC12F683-I/SN075
PIC12F683-I/SNAU

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Affected Catalog Part Number (CPN)

PCN_KSRA-20KRVB706
CATALOG_PART_NBR
PIC12F683T-E/SN
PIC12F683T-E/SN040
PIC12F683T-E/SN079
PIC12F683T-E/SN084
PIC12F683T-E/SN092
PIC12F683T-E/SN097
PIC12F683T-E/SN098
PIC12F683T-I/SN
PIC12F683T-I/SN061
PIC12F683T-I/SN062
PIC12F683T-I/SN072
PIC12F683T-I/SN091
PIC12F683T-I/SNAU
PIC12HV609-E/SN
PIC12HV609-I/SN
PIC12HV609T-I/SN
PIC12HV615-E/SN
PIC12HV615-I/SN
PIC12HV615T-E/SN
PIC12HV615T-E/SN035
PIC12HV615T-E/SN043
PIC12HV615T-E/SN044
PIC12HV615T-I/SN
PIC12HV615T-I/SN022